

2000-313212 NE-1066-US アメリカ UNITED STATES



DECLARATION FOR PATENT APPLICATION Docket No. NECM 19.067

As a below named inventor, I hereby declare that:

My residence, post office add	ress and citizenship are as stated	l below next to my name.	
(if plural names are listed bel	st and sole inventor (if only one ow) of the subject matter which DING STRUCTURES	name is listed below) or an orig n is claimed and for which a pat	inal, first and joint inventor tent is sought on the inven-
the specification of which			
(check one) [X] is atta	ched hereto. led on		as
Appli	cation Serial No.		
and w	as amended on		(if applicable).
I hereby state that I have reclaims, as amended by an ame	viewed and understand the corendment referred to above.	ntents of the above identified s	specification, including the
I acknowledge the duty to diswith Title 37, Code of Federal	sclose information which is ma Regulations, §1.56(a).	terial to the examination of this	s application in accordance
of inventor's certificate listed	benefits under Title 35, United below and have also identified before that of the application of	d States Code, §119 of any forei ed below any foreign application which priority is claimed:	gn application(s) for patent on for patent or inventor's
Prior Foreign Application(s)			Priority Claimed
2000–313212	Japan	13/10/2000	Yes XX
(Number)	(Country)	(Day/Month/Year File	ed)
(Number)	(Country)	(Day/Month/Year File	•
(Number)	(Country)	(Day/Month/Year File	ed) Yes No
I hereby claim the benefit under Title 35, United State Code, §120 of any United States application(s) listed below and, inspfar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: (Application Serial No.) (Filing Date) (Status - patented, pending, abandoned)			
(Application Serial No.	.) (Filing Da	(Status - paten	teu, pending, abandoneu)
(Application Serial No.) (Filing Da	te) (Status - paten	ted, pending, abandoned)
I hereby appoint as my attorney Aaron B. Karas, Reg. No. 18,923 and Samson Helfgott, Reg. No. 23,072 to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:			
Address all correspondence to: HELFGOTT & KARAS P.C. 60th Floor Empire State Building New York, New York 10118-0110 Telephone No. (212) 643-5000			
tion and belief are believed to statements and the like so made	be true; and further that these s de are punishable by fine or im	nowledge are true and that all statements were made with the k prisonment, or both, under Sect ay jeopardize the validity of the	nowledge that willful false ion 1001 of Title 18 of the
Full name of sole or first inver	ntor Takanobu KAI		
Inventor's signature	nou hav Jakanobu	Nai (Date C	october 5, 2001
Residence Tokyo, Jar	oan .	Citize	nship Japanese
Post Office Address C/O N	WEC Corporation, 7-1	Shiba 5-chome. Minato-	ku. Tokvo Japan



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

: Takanobu KAI

Filed:

: Concurrently herewith

For:

: EMI SHIELDING STRUCTURES

Serial No.

: Concurrently herewith

Assistant Commissioner of Patents Washington, D.C. 20231

October 12, 2001

SUB-POWER OF ATTORNEY

SIR:

I, Samson Helfgott Reg. No. 23,072 attorney of record herein, do hereby grant a sub-power of attorney to Linda S. Chan, Reg. No. 42,400, Harris A. Wolin, Reg. No. 39,432, Brian S. Myers, Reg. No. 46,947, Michael Markowitz, Reg. No. 30,659, Shahan Islam, Reg. No. 32,507 and Emma Shleifer, Reg. No. 29,734 to act and sign in my behalf in the above-referenced application.

Respectfully submitted,

(X)Samson Helfgott Reg.No. 23,072

[] Aaron B. Karas

Reg. No. 18,923

Rosenman & Colin LLP 575 Madison Avenue NEW YORK, NY 10022-2585 DOCKET NO.: NECM 19.067